

Claims

1. A method for the production of circuit boards and/or corresponding constructs comprising points at which through-connections in the 20 μm size range are created and, at least in the proximity of said points, strip conductors or an electrically conductive layer are also provided, characterized by the following key method steps:

- drilling of through-bores in the 20 μm size range for the subsequent production of through-connections;
- through-connecting, whereby an electrically conductive general layer is built up;
- etching of the strip conductor image into the electrically conductive general layer;
- filling of the bores of the through-connections with a standard medium;
- lacquering of the surfaces on which through-connections are present and, at least in the proximity of which, strip conductors are later provided;
- applying of insulating lacquer (ISO lacquer), which is a standard medium, to the surfaces of the circuit board and/or of the corresponding construct;
- producing of strip conductors arranged above the through-connections;
- testing of the circuit board and/or of the corresponding construct;
- separating of the individual circuit board and/or of the corresponding construct.

2. The method as claimed in claim 1, characterized in that the standard medium is identical in each of the different method steps.

3. The method as claimed in claim 1 or claim 2, characterized in that the standard medium in the different method steps is in each case a low-cost lacquer variant.

4. The method as claimed in any one of the preceding claims, characterized in that at least the strip conductors arranged above the through-connections are realized with carbon (3).

5. The method as claimed in any one of the preceding claims, characterized in that the separation of the individual circuit boards and/or of the corresponding constructs is accomplished by means of a milling process.